

## Product Information Sheet EPO-TEK® B9021

Date:September 2017Rev:IIINo. of Components:SingleMix Ratio by Weight:N/ASpecific Gravity:1.35Pot Life:28 Days (closed container)Shelf Life- Bulk:One year refrigerated

Recommended Cure: B-stage: 75°C/30 Minutes Cure: 150°C/1 Hour

## NOTES:

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A single component, B-stageable epoxy paste for semiconductor, microelectronics, and optical assemblies. It can be used in hybrid assemblies for lid-sealing and substrate attach. It can be used as the main gasket seal of glass plates in LCDs or sealing filter windows onto opto-sensors.

## Typical Properties: Cure condition: B-stage: 75°C/30 Minutes - Cure: 150°C/1 Hour Data below is not guaranteed.

To be used as a guide only, not as a specification. Different batches, conditions & applications yield differing results.

\* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):		White	
* Consistency:		Smooth paste	
* Viscosity (23°C) @ 50 rpm:		4,000 - 8,000	cPs
Thixotropic Index:		3.9	
Glass Transition Temp:		≥ 60	°C
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	36	x 10 <sup>-6</sup> in/in°C
	Above Tg:	57	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:		76	
Lap Shear @ 23°C:		986	psi
Die Shear @ 23°C:		≥ 4	Kg 1,422 psi
Degradation Temp:		313	°Č
Weight Loss:			
	@ 200°C:	3.77	%
	@ 250°C:	4.41	%
	@ 300°C:	7.97	%
Suggested Operating Temperature: < 260		< 260	°C (Intermittent)
Storage Modulus:		229,854	psi
* Particle Size:		≤ 20	microns

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product. EPOXY TECHNOLOGY, INC. 14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782 www.epotek.com